TOSHIBA BIPOLAR LINEAR INTEGRATED CIRCUIT SILICON MONOLITHIC

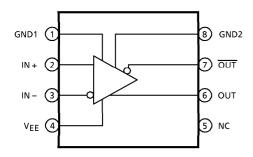
TA8504F

HIGH SPEED COMPARATOR

FEATURES

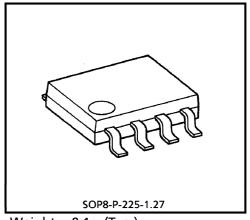
- Pulse delay: 1.6ns (Typ.)
- Differential ECL output
- 50Ω Line drive output
- 8pin mini flat package
- −5V single power supply

BLOCK DIAGRAM



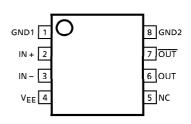
MAXIMUM RATINGS (Ta = 25° C)

			1
CHARACTERISTIC	SYMBOL	RATING	UNIT
Supply Voltage	V_{EE}	0.3~ - 6.0	V
Differential Input Voltage	DV_IN	±3	V
Common Mode Input Voltage	CMVIN	−0.3~V _{EE}	V
Power Dissipation	PD	(*) 300	mW
Operating Temperature	T _{opr}	- 20∼8 5	°C
Storage Temperature	T _{stg}	- 55∼150	°C



Weight: 0.1g (Typ.)

PIN CONNECTION (TOP VIEW)



Recommended Operating Voltage : $V_{EE} = -5.5 \sim -4.5 \text{V}$, $T_{a} = -20 \sim 70 ^{\circ} \text{C}$

(Note *) Shown here is data for the single unit of IC only and when mounted on a substrate, power dissipation can be made larger than this. However, as it varies largely depending upon the state of mounted on a substrate, it shall be examined thoroughly.

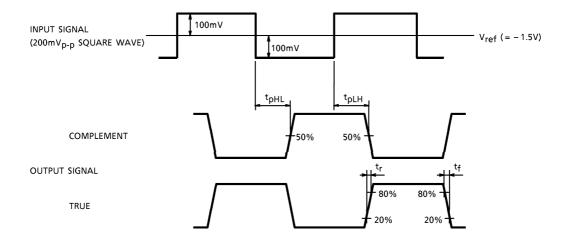
(Note **) As this product is weak to surge voltage, please handle carefully.

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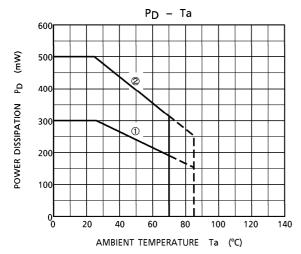
ELECTRICAL CHARACTERISTICS (V_{EE} = -5V, R_L = 50Ω , Ta = 25° C)

CHARACTE	ERISTIC	SYMBOL	TEST CIR- CUIT	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Input Offset Vo	ltage	_	_	R_S <500 Ω	- 10	_	10	mV
Input Bias Curre	ent	_	_	_	_	20	40	μΑ
Input Offset Cu	rrent	_	_	_	_	_	10	μΑ
Supply Current		IEE	_	$V_{EE} = -5.5V$	_	26	37	mA
Propagation Delay		t _{pLH}	_	(Note 1)	_	1.6	2.6	ns
		t _{pHL}	_	(Note 1)	_	1.6	2.6	
Rise Time	20~80%	t _r	_	(Note 1)	_	1.0	1.8	
Fall Time	20~80%	tf		(Note 1)	_	0.7	1.6	ns
Common Mode Voltage Range	Input	_	_	_	- 2.5	_	- 0.8	V
Output Voltage		Voн	_	$R_L = 50\Omega$ is load per -2V.	- 1.025	_	- 0.88	V
		VOL	_		- 1.81	_	- 1.62	
Input Capacitan	ce	_	_	_	_	3.5	_	рF
Open Loop Gai	n	_	_	_	_	70	_	dB

(Note 1) Input/Output conditions are as illustrated below.

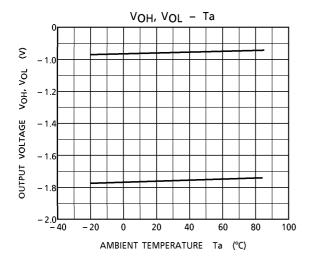


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(Note 1) ① is data of a single unit of IC only.

(Note 2) @ is reference data when mounted on a glass epoxy resion substrate in $20\times20\times1.8$ mm³, and the copper laminted area is 60% of the substrate.



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PACKAGE DIMENSIONS

SOP8-P-225-1.27 Unit : mm

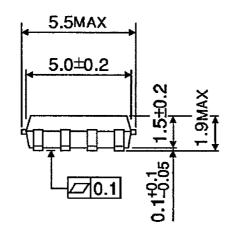
8

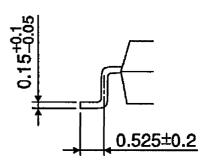
1.27

Unit : mm

0.595TYP

1.27





Weight: 0.1g (Typ.)

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RESTRICTIONS ON PRODUCT USE

000707EBA

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